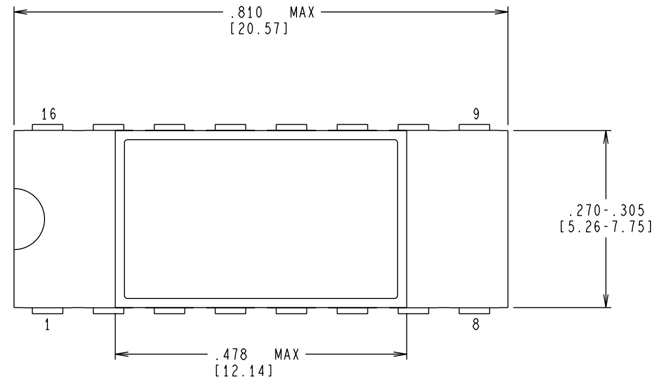
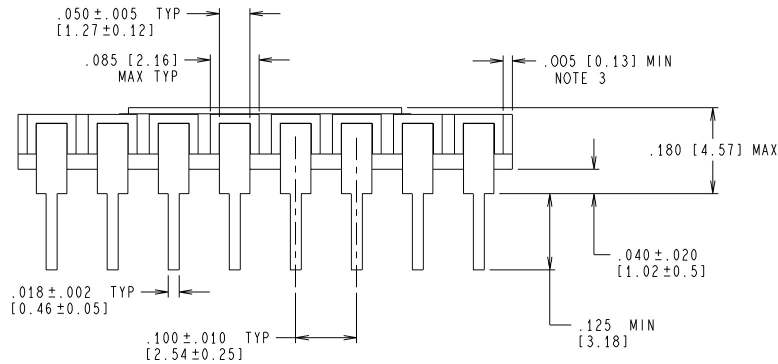
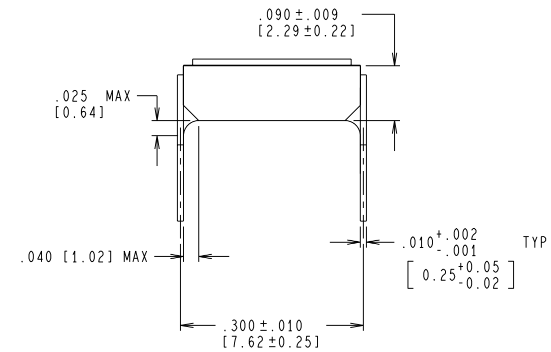
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
J	REVISE AND REDRAW PER NEW STANDARD.	10258	02/16/94	DEG/TP
K	.085 MAX WAS .080±.008;.270-.305 WAS .290 ± .003.	10475	10/10/94	DEG/







CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
   a. 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
   b. 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
3. DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
4. REFERENCE JEDEC REGISTRATION MS-015, VARIATION AC, DATED 7/90.

MIL-M-38510
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN *Dwayne Grady*	10/10/94
DFTG. CHK.	
ENGR. CHK.	

PROJECTION
INCH [MM]

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

DIP, SIDEBRAZED CERAMIC, 16 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-D16C	K

DO NOT SCALE DRAWING

SHEET 1 of 1

INP
SEAL R
LID
LID RA
LEADCO
BODY LE
BODY WI